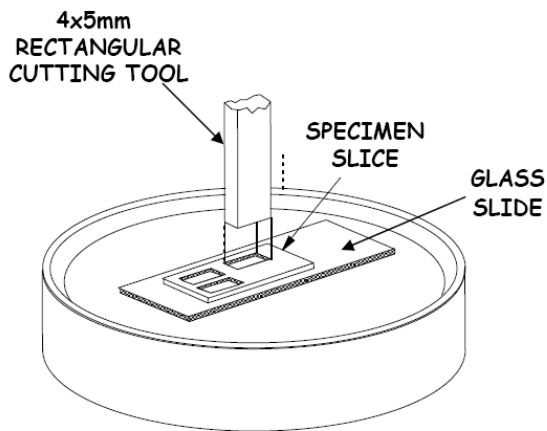
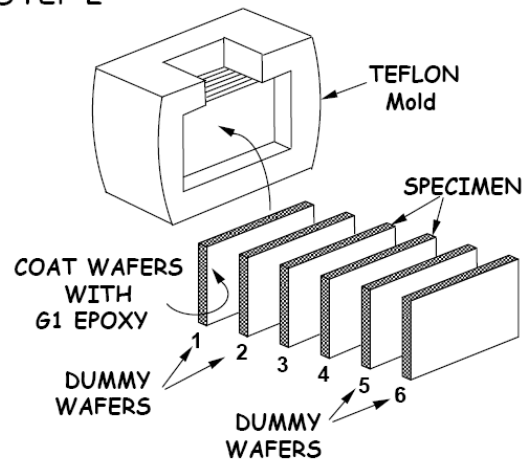


### STEP 1



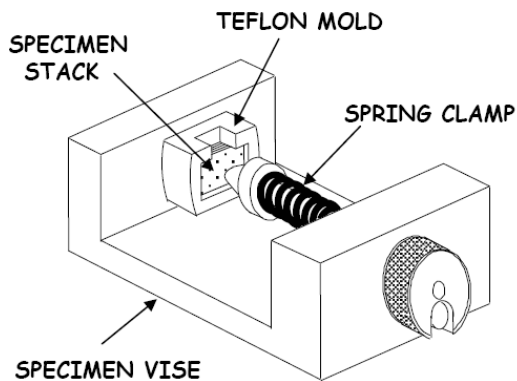
Cut rectangular wafers from bulk material using ultrasonic disc cutter

### STEP 2



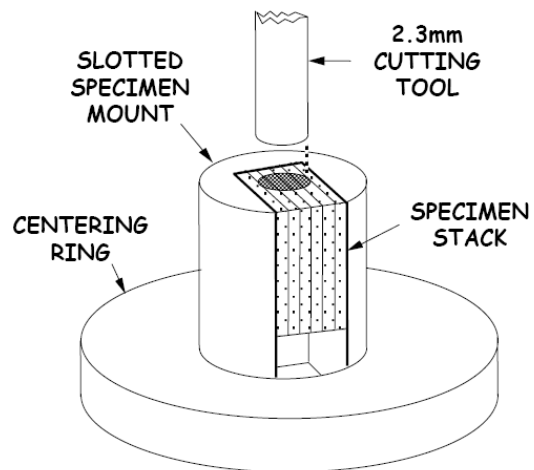
Coat all wafers with a thin layer of G-1 & load into Teflon™ mold

### STEP 3



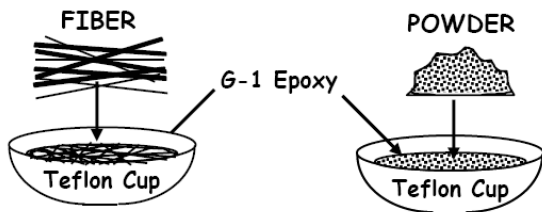
Cure glued stack under pressure to form a strong bond between wafers.

### STEP 4



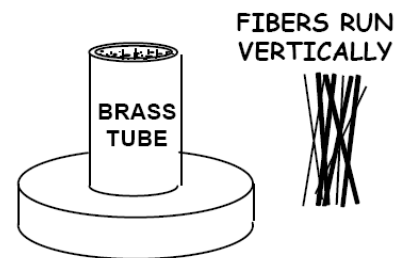
Cut cylinder from stack using ultrasonic disc cutter

### Step 1



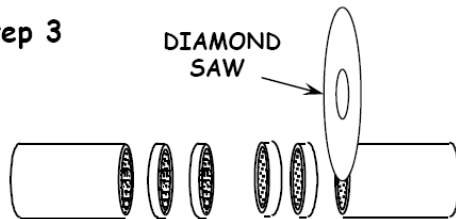
Mix G-1 epoxy with fibers or powder transfer mixture to a brass tube

### Step 2



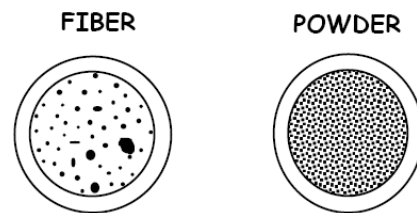
Cure epoxy on hot plate for 10 minutes at 130°C

### Step 3



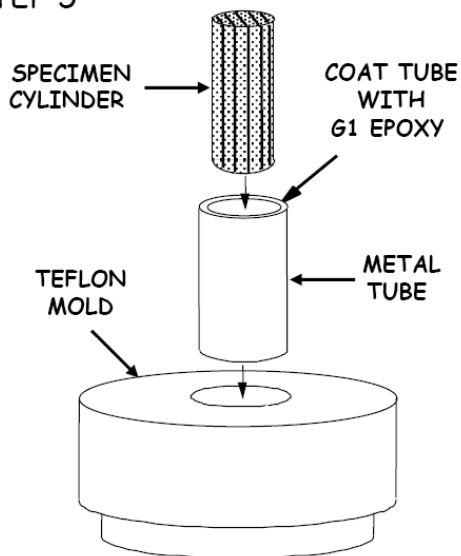
Cut brass tube into disc's for grinding to required thickness

### Step 4



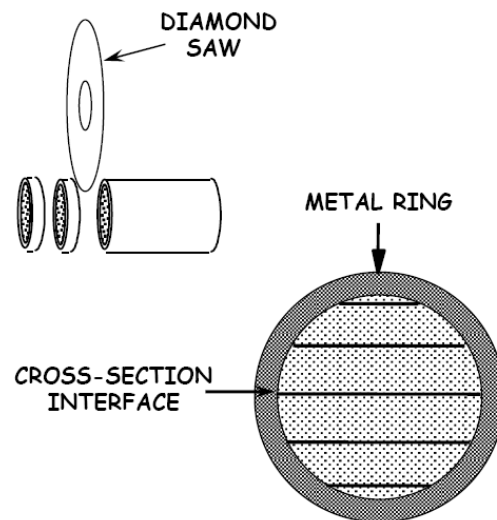
Disc grind, dimple grind and ion mill to perforation

### STEP 5



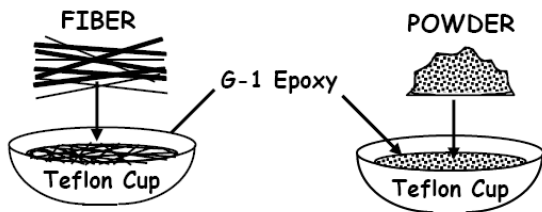
Glue cylinder inside metal tube. Cure on hot plate.

### STEP 6



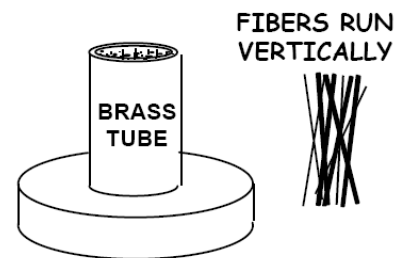
Sliced specimen discs ready for disc grinding and dimpling.

### Step 1



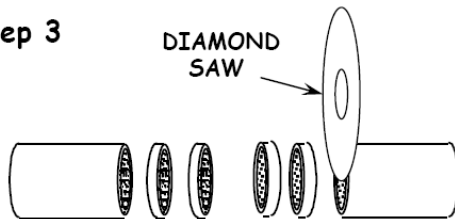
Mix G-1 epoxy with fibers or powder  
transfer mixture to a brass tube

### Step 2



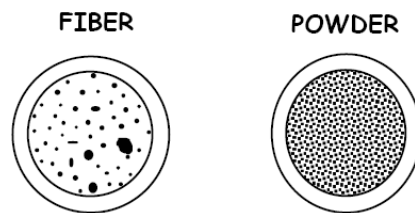
Cure epoxy on hot plate for  
10 minutes at 130°C

### Step 3



Cut brass tube into disc's  
for grinding to required thickness

### Step 4



Disc grind, dimple grind and  
ion mill to perforation